



Semiconductor Device Type: RLB-VQFN-24-4x4x0.9mm-MatteTin

Material	Substance	CAS Number	Mass of Substance in Material (mg)	Mass of Material (mg)	Percentage of Substance in Material	Percentage of Material in Product	Percentage of Substance in Product	Amount of Substance in Product (ppm)
Die				3.18	100.00%	7.68%		
	Silicon	7440-21-3	3.18		100.00%		7.68%	76810
Mold Compound				20.60	100.00%	49.77%		
	Epoxy Resin	Trade Secret	1.44		7.00%		3.48%	34836
	Phenolic Resins	Trade Secret	1.03		5.00%		2.49%	24883
	Silica (Fused)	60676-86-0	15.45		75.00%		37.32%	373242
	Silicon Dioxide	7631-86-9	1.44		7.00%		3.48%	34836
	Metal Hydroxide	Trade Secret	1.03		5.00%		2.49%	24883
	Carbon Black	1333-86-4	0.21		1.00%		0.50%	4977
Lead Frame				16.34	100.00%	39.48%		
	Copper	7440-50-8	15.91		97.36%		38.44%	384369
	Iron	7439-89-6	0.40		2.42%		0.96%	9558
	Lead	7439-92-1	0.00		0.01%		0.00%	42
	Phosphorus	7723-14-0	0.02		0.11%		0.04%	416
	Zinc	7440-66-6	0.02		0.11%		0.04%	416
Die Attach Epoxy				0.07	100.00%	0.16%		
	Silver	7440-22-4	0.05		67.90%		0.11%	1116
	Carbocyclic Acrylate	Trade Secret	0.01		20.00%		0.03%	329
	Bismaleimide Resin	Trade Secret	0.00		5.50%		0.01%	90
	Acrylate or Acrylic	Trade Secret	0.00		5.50%		0.01%	90
	Epoxyoctahydroethyltrimethoxysilane	3388-04-3	0.00		0.55%		0.00%	9
	Palladium Compound	Trade Secret	0.00		0.55%		0.00%	9
Plating and Anode Ball				0.76	100.00%	1.85%		
	Lead	7439-92-1	0.00		0.05%		0.00%	9
	Tin	7440-31-5	0.76		99.95%		1.85%	18450
Bond Wire				0.07	100.00%	0.18%		
	Gold	7440-57-5	0.00		1.00%		0.00%	18
	Palladium	7440-05-3	0.00		3.00%		0.01%	54
	Copper	7440-50-8	0.07		96.00%		0.17%	1716
Lead Frame Plating				0.37	100.00%	0.88%		
	Silver	7440-22-4	0.37		100.00%		0.88%	8843
Totals			41.39	41.39		100.00%	100.00%	100000

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